

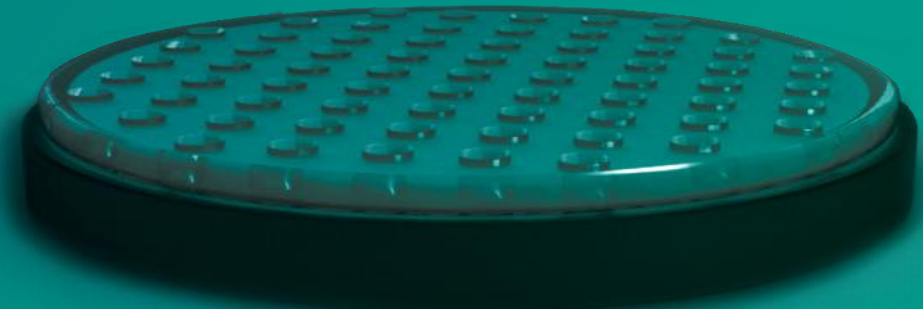
SCIL technology for direct patterning of functional optics

EPIC meeting Neuchatel 2019

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Rob Voorkamp, SCIL team

November 7, 2019

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Contents

- SCIL Nanoimprint Solutions
- SCIL technology and materials
- Tooling and roadmap
- Pattern uniformity
- Conclusions

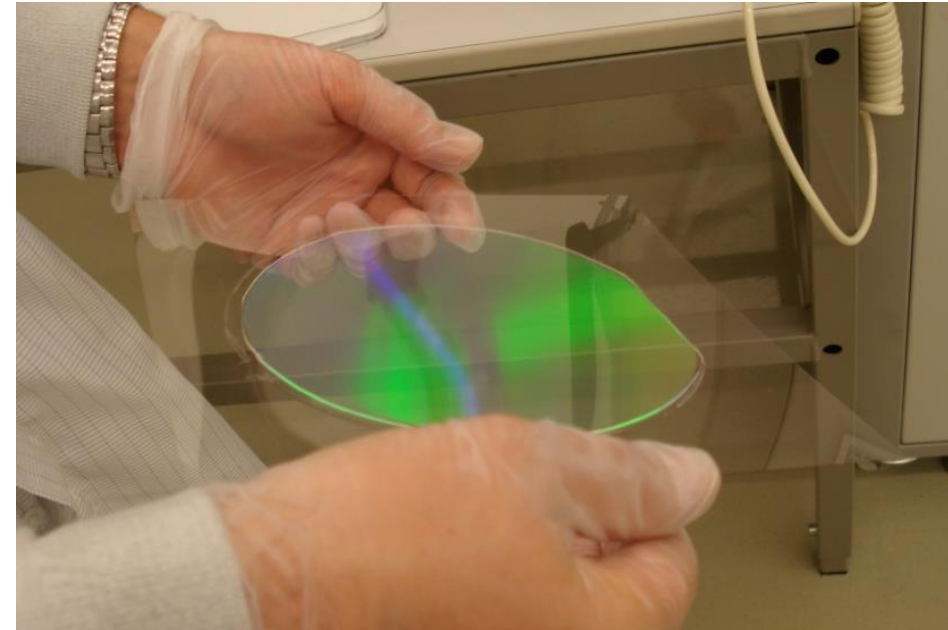
SCIL Nanoimprint solutions

- Developed in Philips research from 2001, SCIL venture start in 2015
- SCIL is a unique and proprietary technology for **nanoprint and nanoimprint lithography**
- SCIL Nanoimprint solutions **for wafer scale nano patterning**
 - Imprint tools for low and high volume production
 - Stamp materials or ready-to-use stamps
 - NanoGlass® resists
 - Customer specific SCIL processes
- This enables our customers to **increase performance and lower costs** of their products
- Our customers include manufacturers of LEDs, lasers, optical components, solar cells, bio-sensors and many others



Substrate Conformal Imprint Lithography (SCIL)

- Substrate conformal NIL solution
 - The only real conformal imprint technology
- Composite stamp sub-10nm resolution
 - Flexible enough to follow substrate non-flatness
 - Hard enough to achieve nano structures
- Unique Imprint process
 - Sequential low pressure imprint cycle. Capillary force driven
 - $\sim 1.5\mu\text{m}$ overlay alignment over 200mm wafer
- Full inorganic imprint resist (NanoGlass[®])
 - Good etch resistance, thermal stability, optical transparent and UV stable
 - Stamp lifetime > 500 imprints for sub-50nm patterns

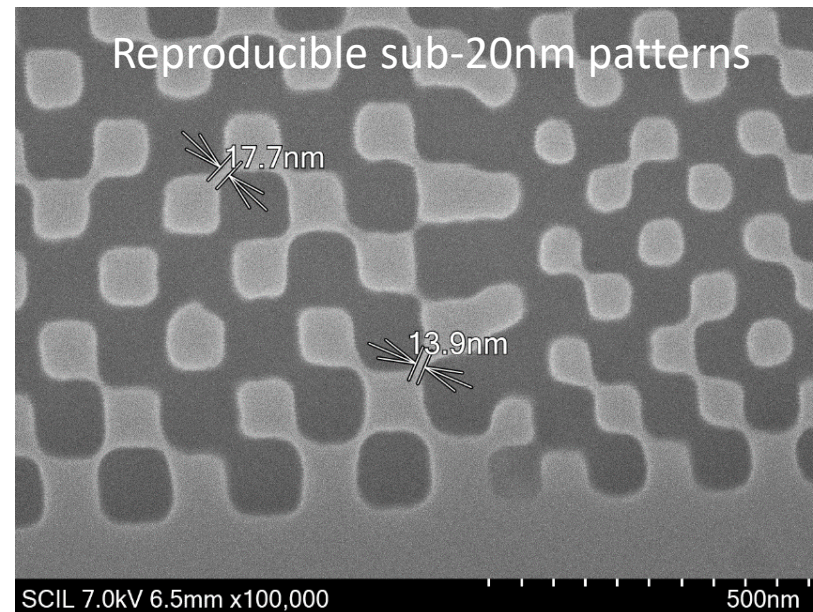
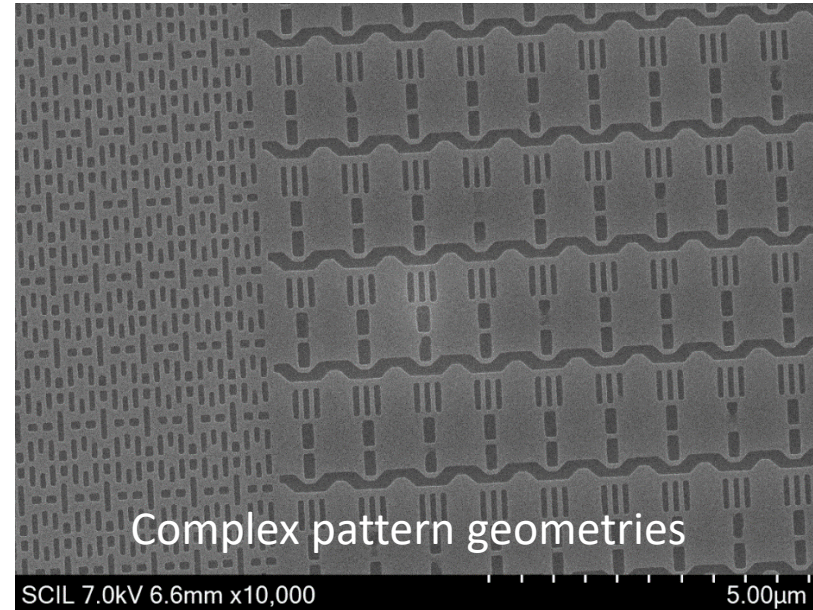
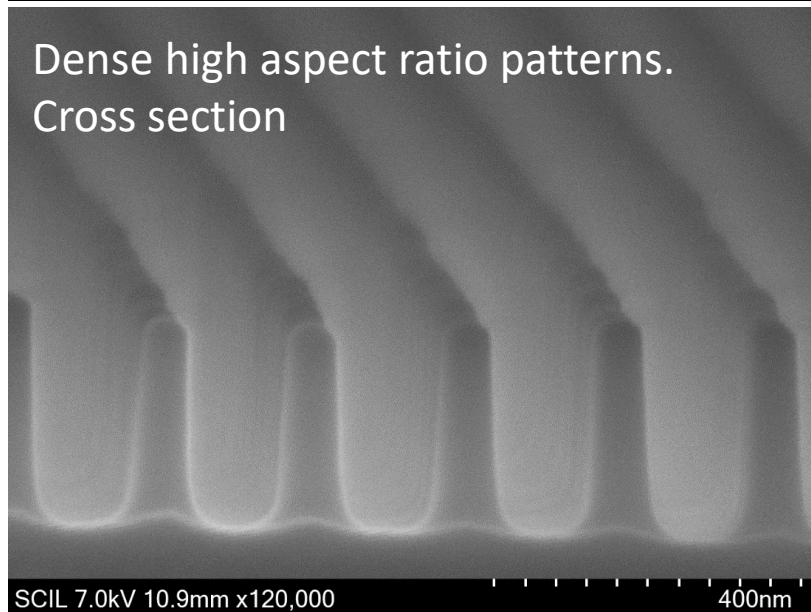
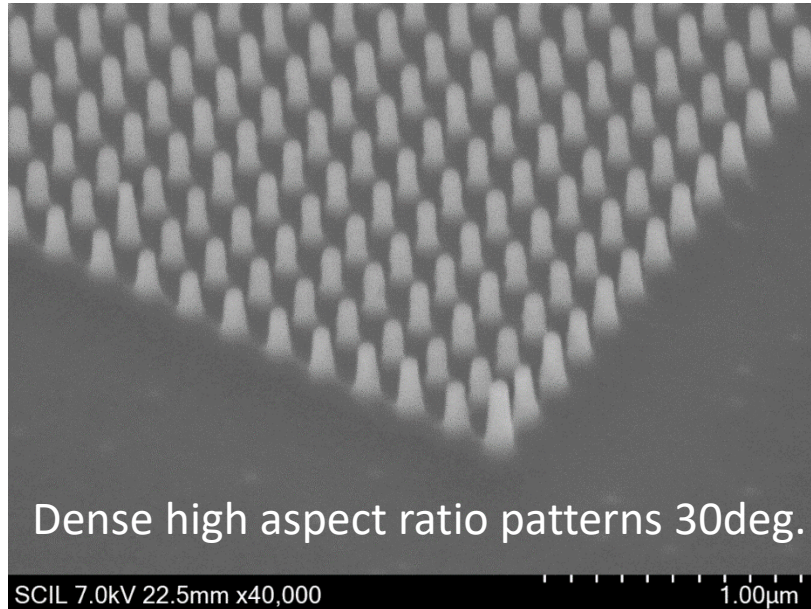


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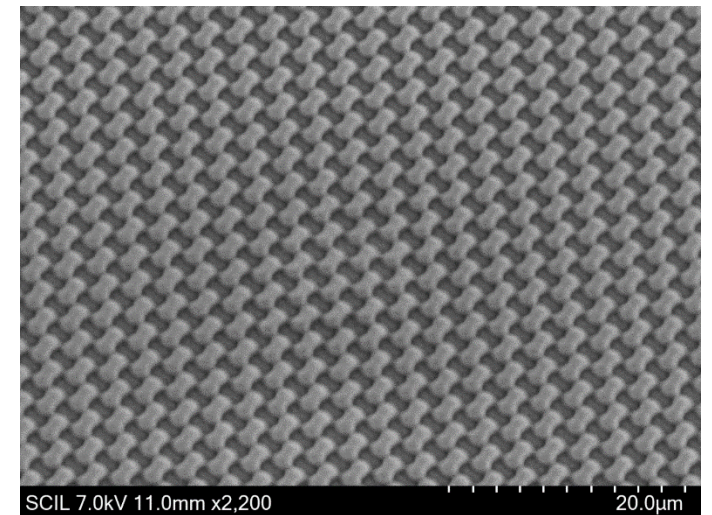
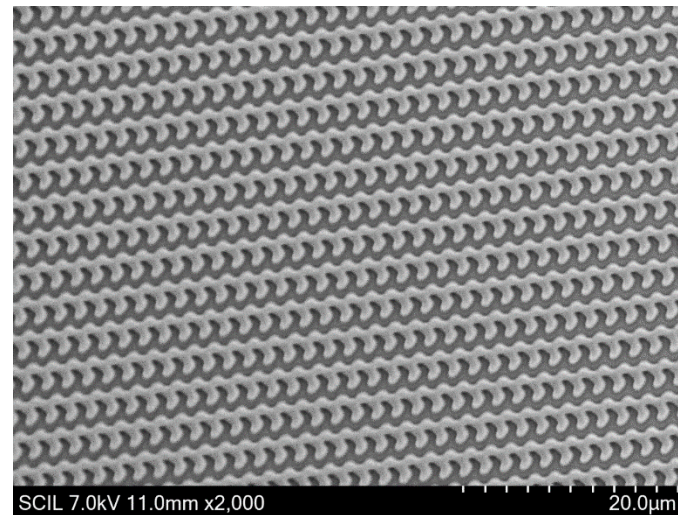
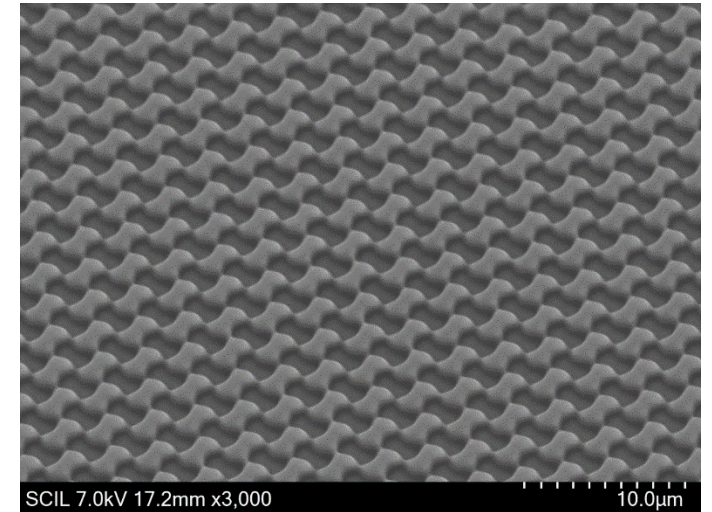
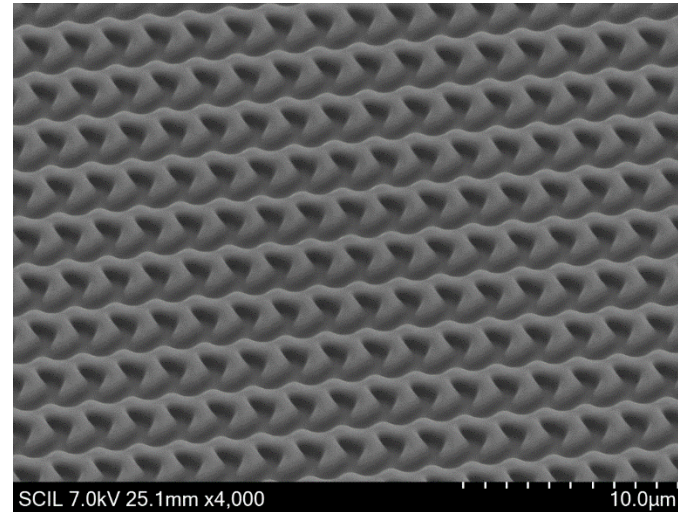


Variety of patterns

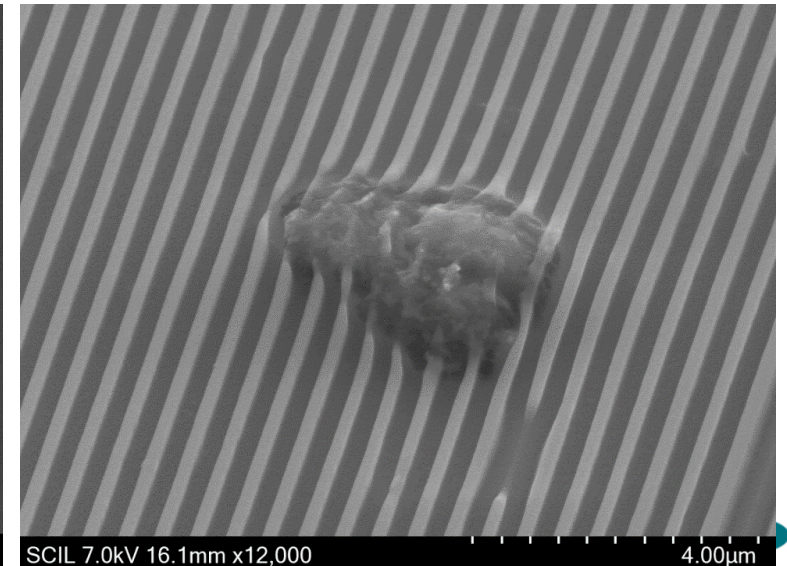
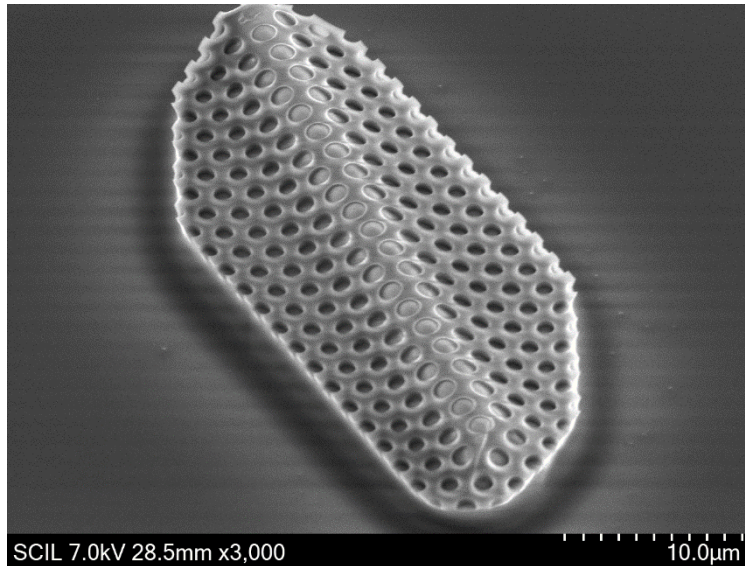
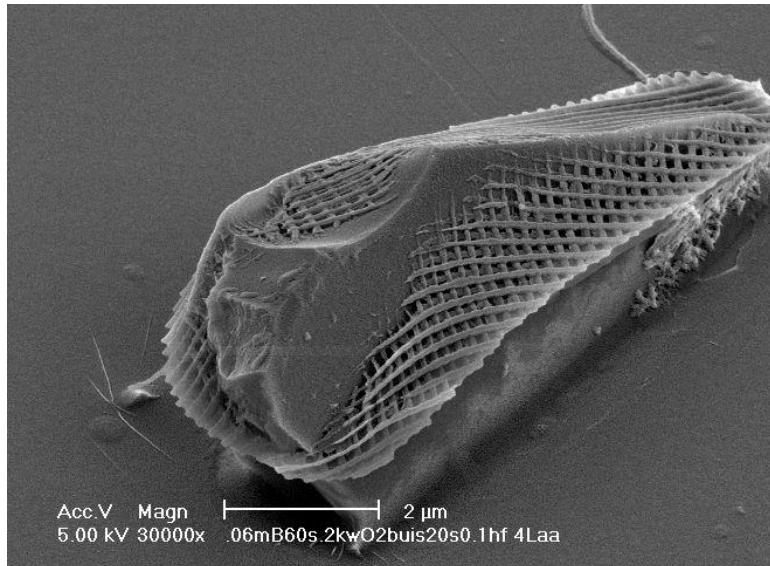
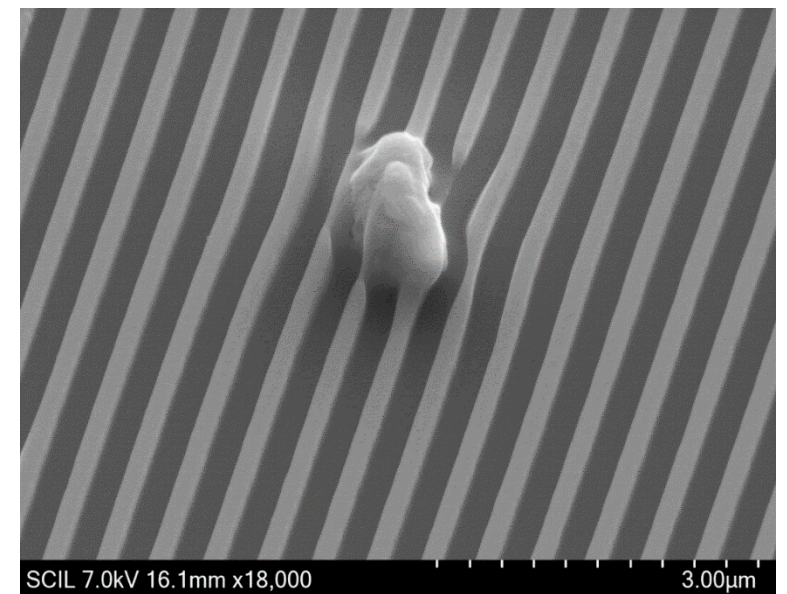
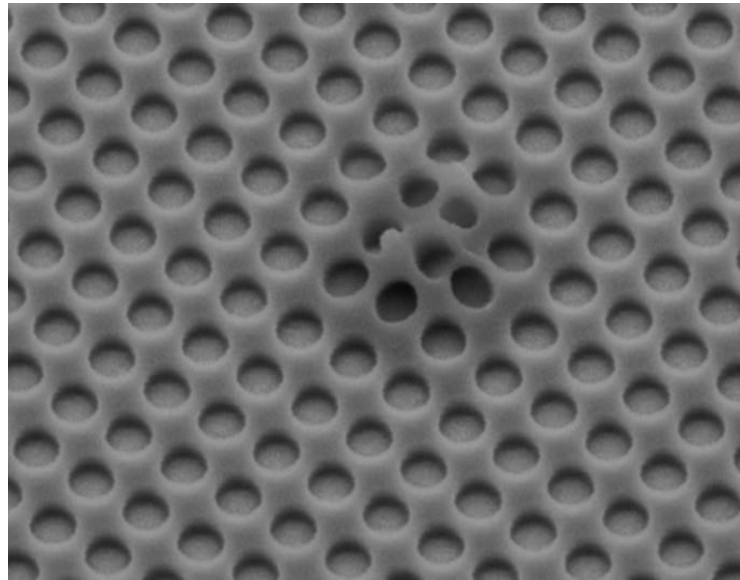
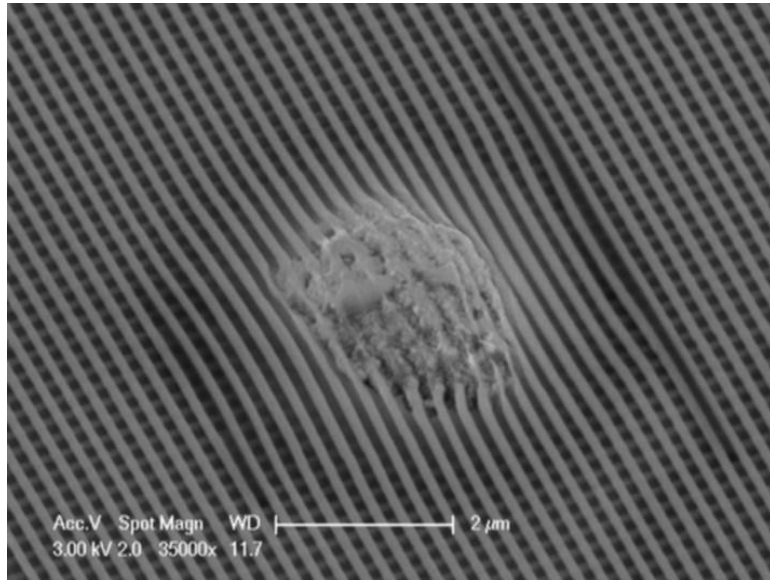


DOEs on glass and COP

- Dot pattern generation
- Tape test passed on COP and glass
- ~1 micron high patterns
- Curtesy to CDA GmbH – Germany



Substrate Conformal, self cleaning, stamp lifetime >500 imprints



SCIL Tooling

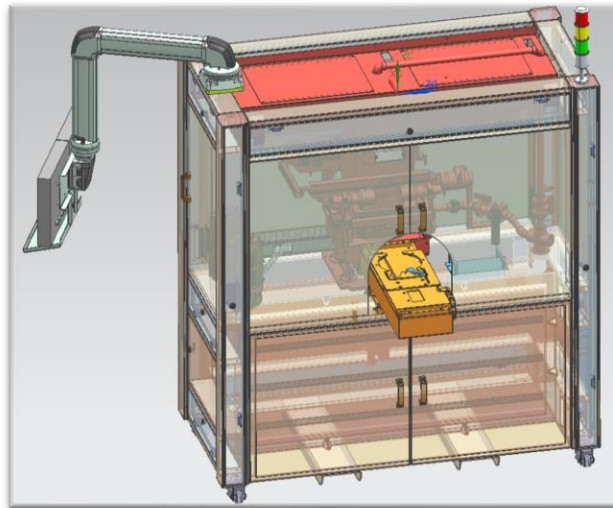
AutoSCIL

- Fully integrated system including all process steps : wafer handling, aligning, spin-coating, SCIL imprint, baking and cooling.
- Specifications:
 - 75, 100, 150, 200mm wafers
 - 30-60 waf./hr using NanoGlass UV & thermal curing
 - Wafer scale overlay alignment



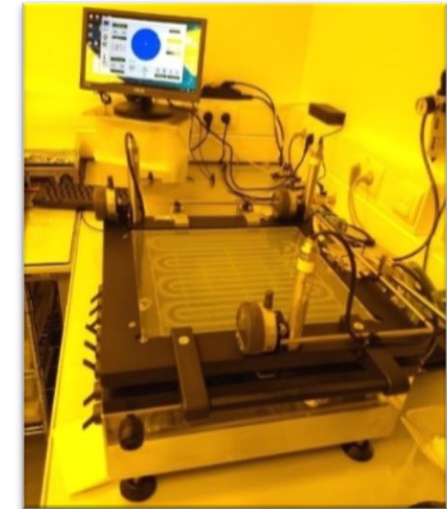
LabSCIL

- Stand-alone SCIL imprint unit for R&D and low volume production
- Specifications:
 - Processing: 100, 150, 200mm wafers
 - Low volume
 - UV & thermal curing
 - Wafer scale overlay alignment



Stamp making tools

- Stamp Making Tool to make SCIL composite stamps
- Specifications:
 - Size: 2", 3", 100mm, 150mm, 200mm
 - Uniform heating
 - Manual and semi automatic tools available



Roadmap stamp tooling

- 300mm semi-automatic stamp making
 - Compact stand alone
 - Increased level of automation
 - Extensive logging for quality control
 - Enhanced thermal control
 - Absolute
 - Uniformity
- Fully automatic stamp making
 - 200 and 300mm stamps
 - Library of masters
 - Finished stamp in clean box out
 - ~4 stamps / h



Available in Q1 2020

Available in 2022

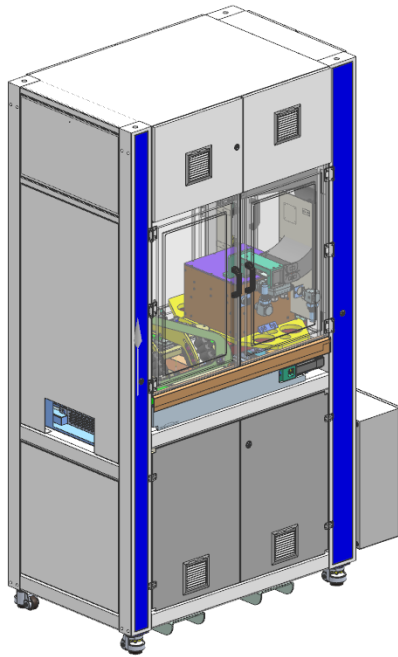


(artist impression)

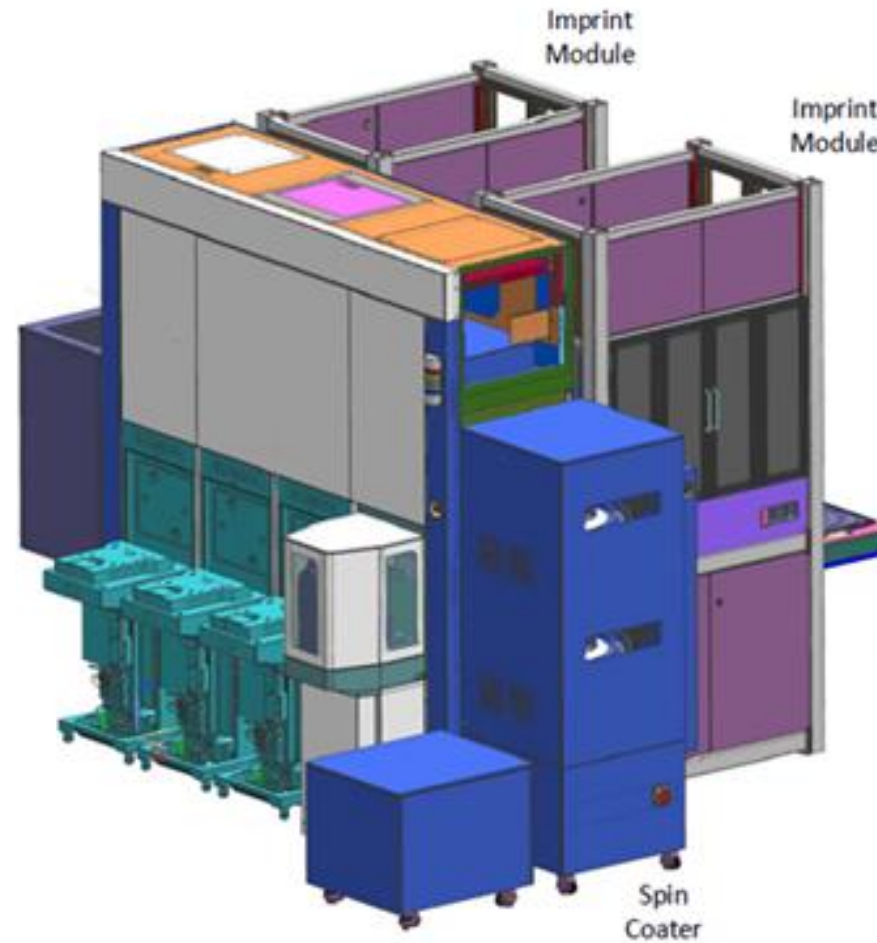
Roadmap SCIL Imprint tooling

AutoSCIL300

- 200mm & 300mm wafers
- Automatic stamp loading
- Available Q2 2020



200/300mm
imprint module

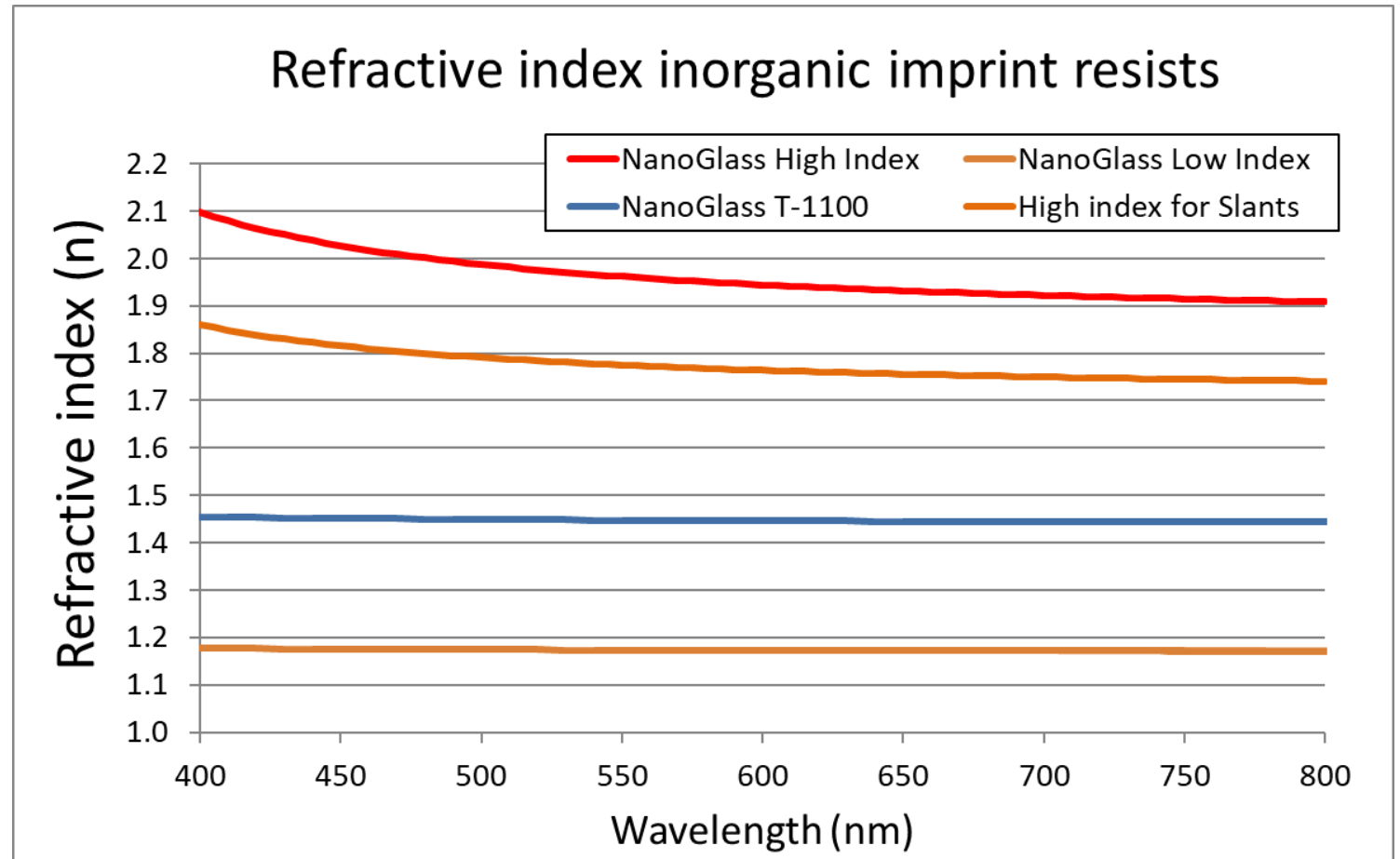


200/300mm cluster
tool with two imprint
modules

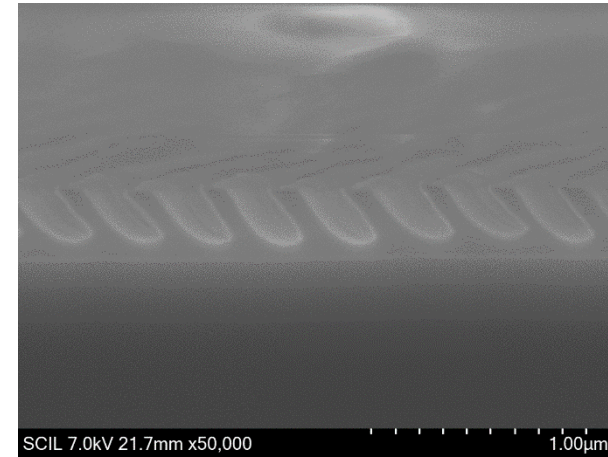
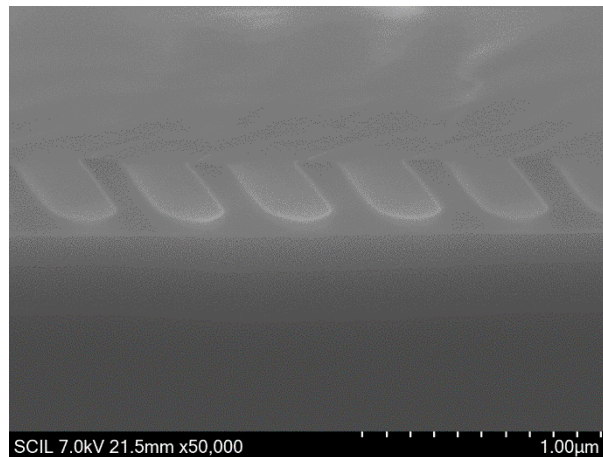
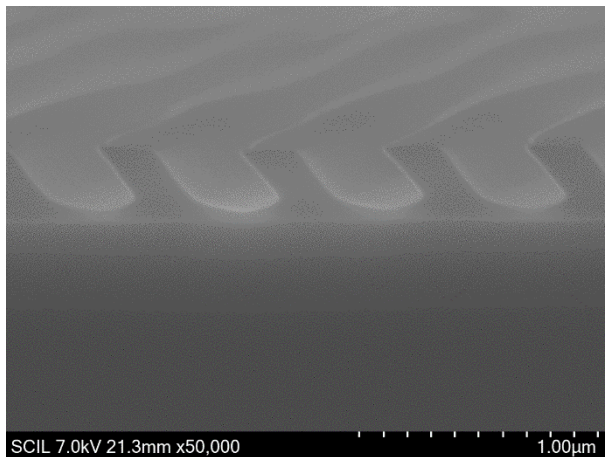
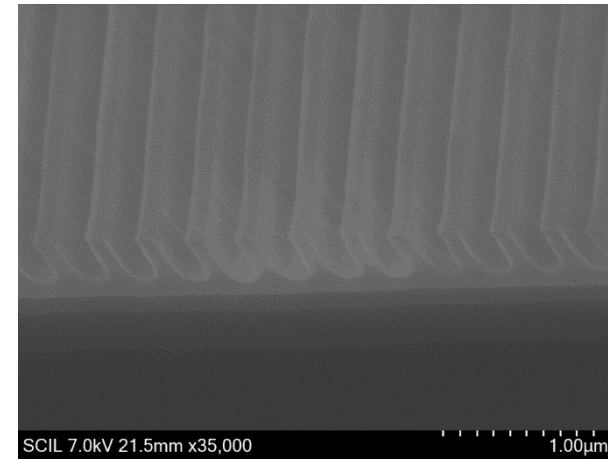
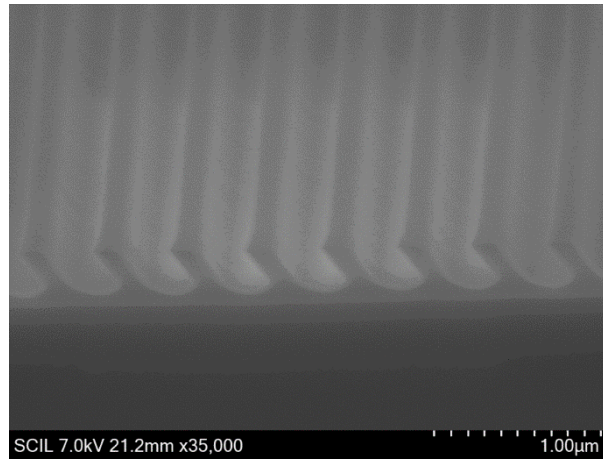
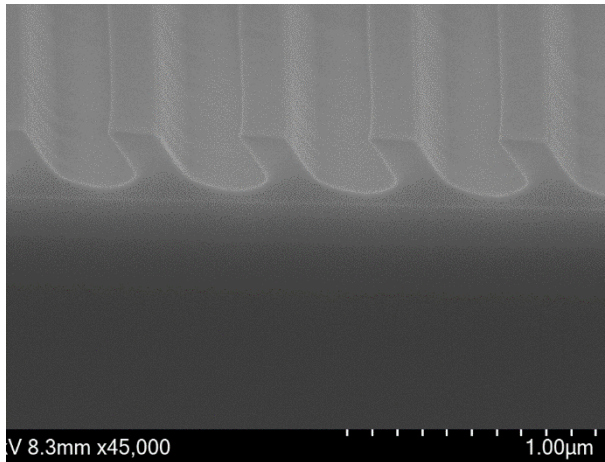
Inorganic functional optical materials

Directly patterning optical materials – new range in refractive index

- All resist types are fully inorganic
 - Index range $n=1.17$ to **2.1**
 - Robust
 - Non-absorbing down to $\lambda \sim 360\text{nm}$
 - Temperature stable $>400^\circ\text{C}$
- Low shrinkage $<10\%$
- For metasurfaces / flat lenses
- Key figure or merit:
nm-reproducible features



Slanted grating imprint in NanoGlass T-1250



- Slanted gratings
- Slant angle $\sim 35^\circ$ off normal
- Vertical: $\sim 260\text{nm}$
- Master provided by NIL Technology Denmark

Period: 600nm

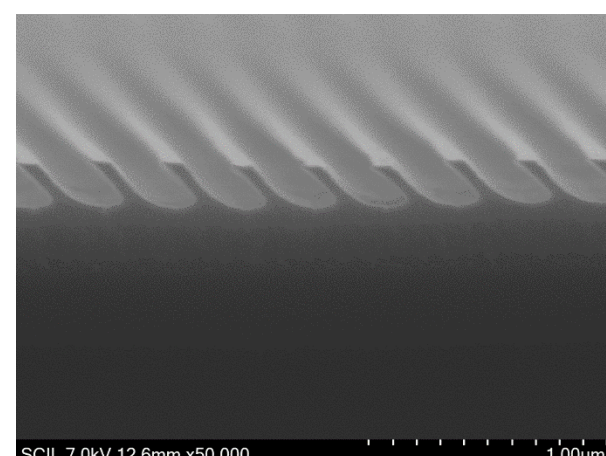
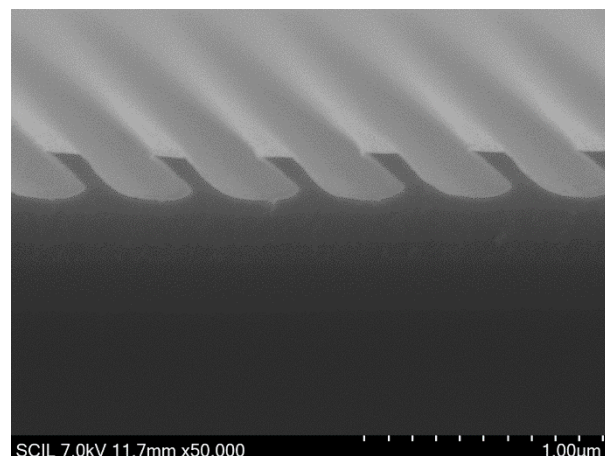
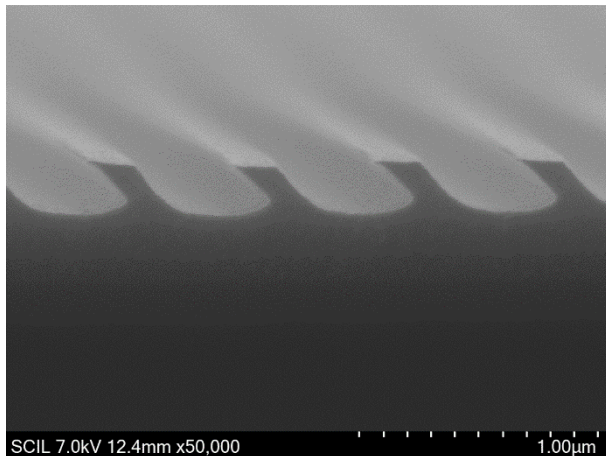
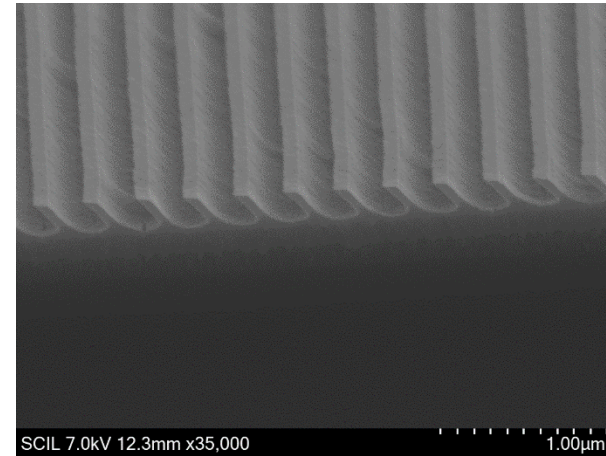
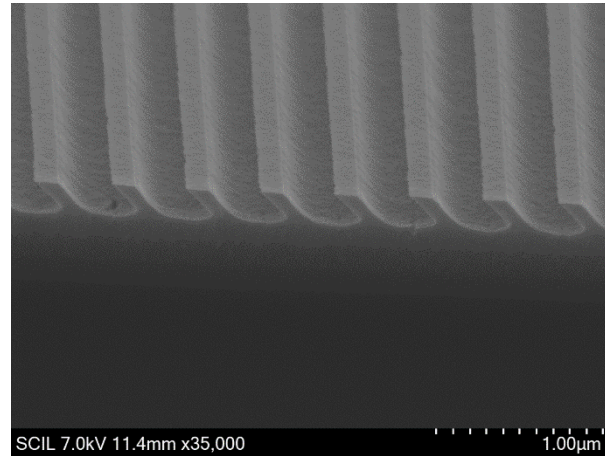
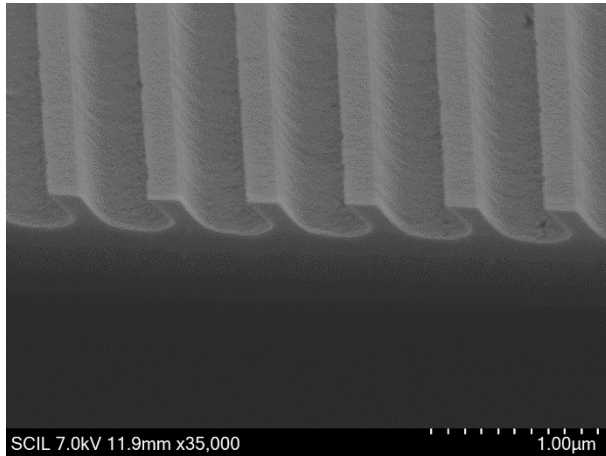
450nm

300nm



Stamp lifetime > 100 imprints proven. Expect to reach same as binary ~ 500

Slanted grating imprint in NanoGlass high index ($n=1.8$)



Period: 600nm

450nm

300nm



Slightly more shrinkage than T-1250, developments to reach $n > 1.8$

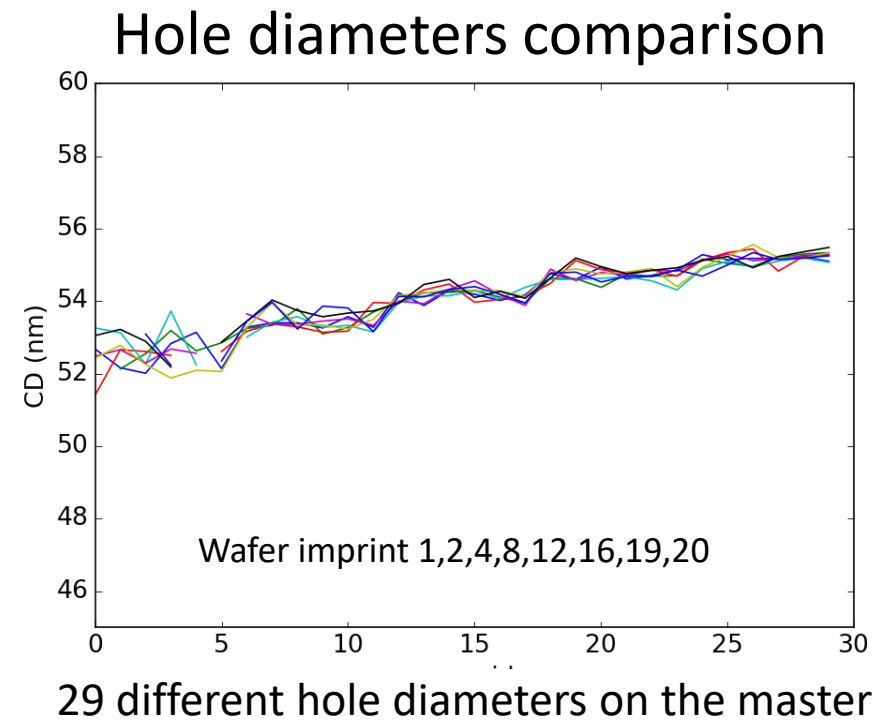
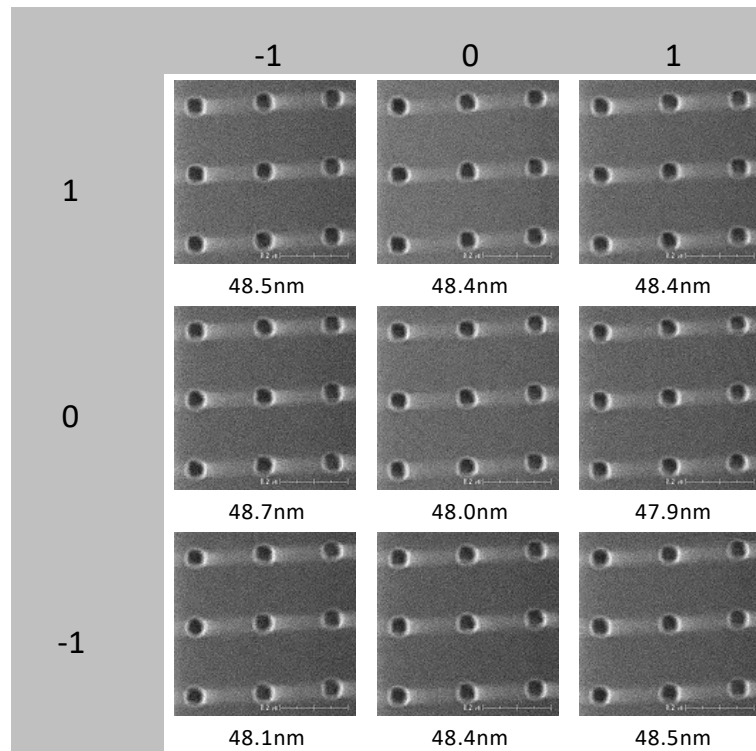
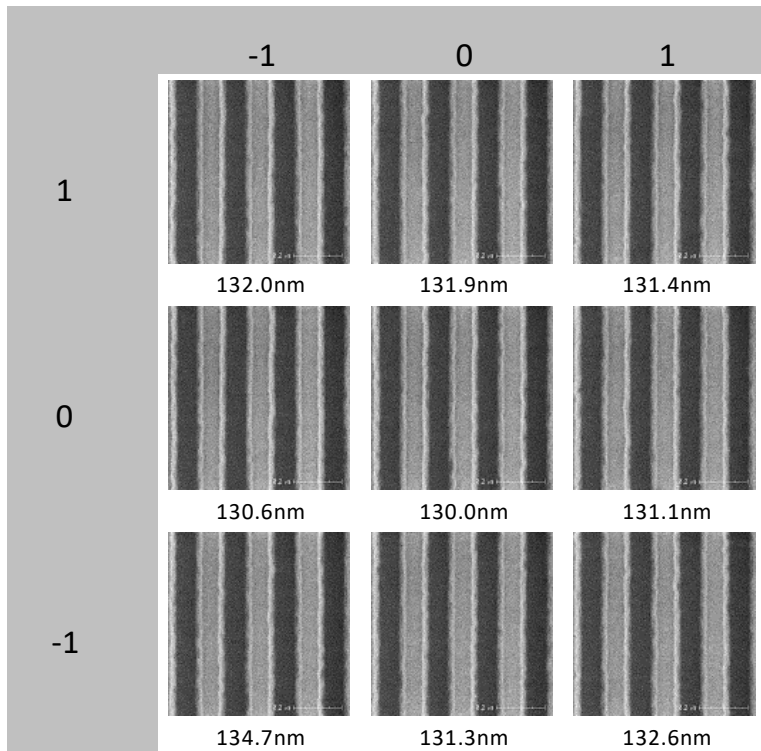
SCIL | Confidential



Pattern uniformity evaluation

CD-SEM pattern evaluation in cooperation with CEA / Leti

- Single, dense, ~40nm to micro's
- Hole arrays 52nm diameter, 120nm deep
- Imprints 1 through 20 of 3^e X-PDMS stamp from the master → ~1nm variations



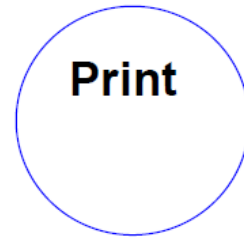
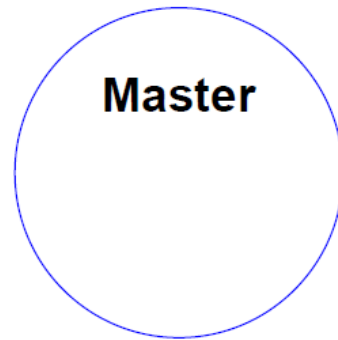
Conclusions

- SCIL provides NIL based high volume production solutions up to 300mm (2020 Q2)
- Cost effective solution due to optimized combination of tool, process and materials
- Direct replication of complex sub-micron patterns in inorganic optical materials is key enabler for nano-photonics – from low to high index
- We work with customers from: proof of concept to pilot-volumes and transfer to high production

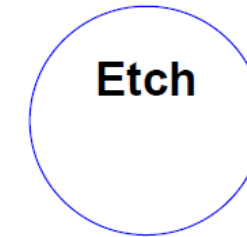




Master Replication with Precision

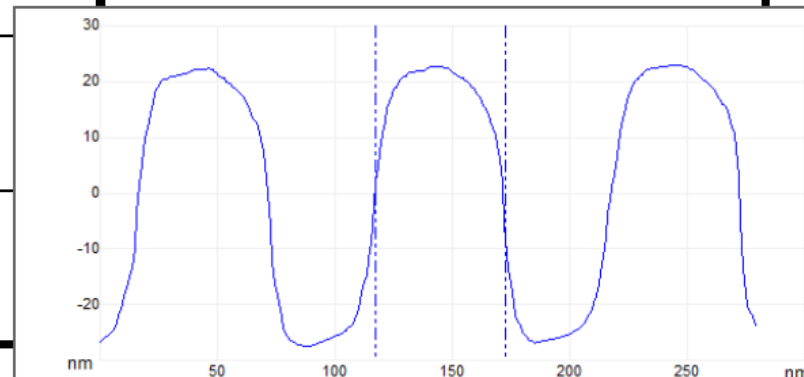


Post Etch CD Bias
is etch process
dependent



CD Data in nm

$\bar{\chi}$	47.64	45.19
σ	2.19	1.12
n	13	229



$\bar{\chi}$	53.94
σ	2.07
n	15

Print to print variation, sub-50nm patterns

13 locations over a 200mm wafer

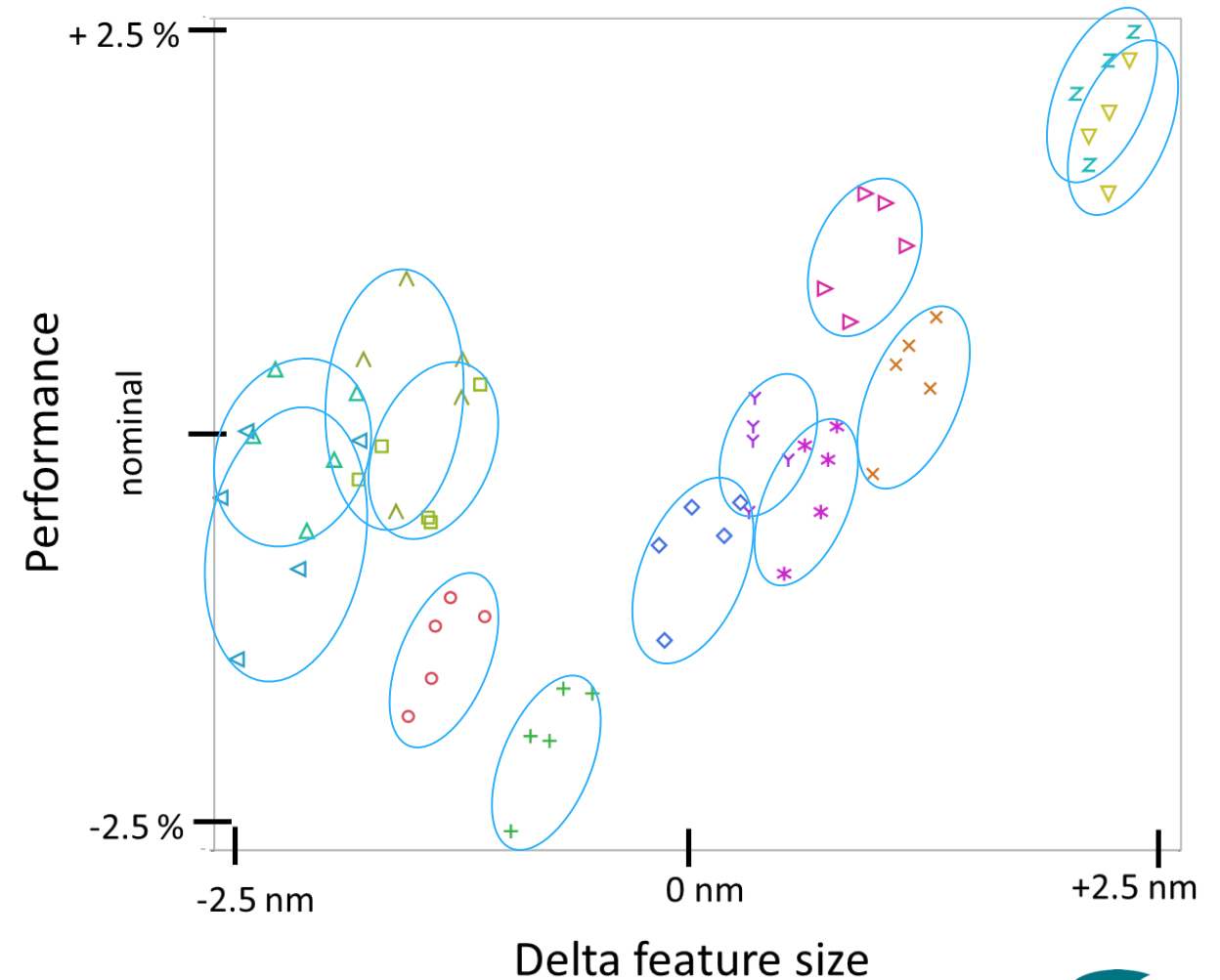
- Product performance highly sensitivity to pattern size
- There is pattern size variations in the master pattern
- We want to know the SCIL induced variation

Measurements:

- 13 locations over a 200 mm wafer
- 5 imprinted wafers (from batch of 25)
- Sub-50nm patterns

Results:

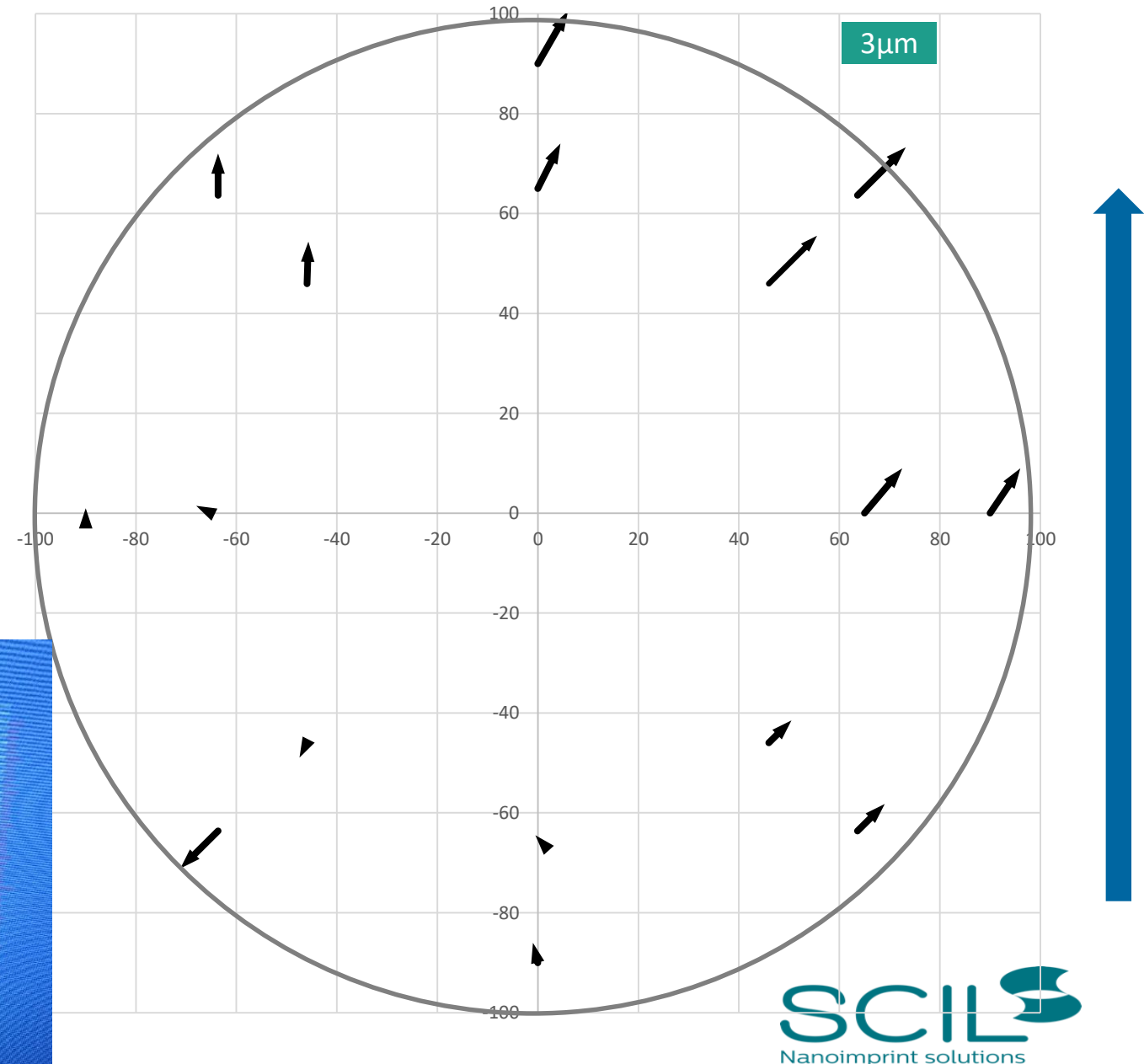
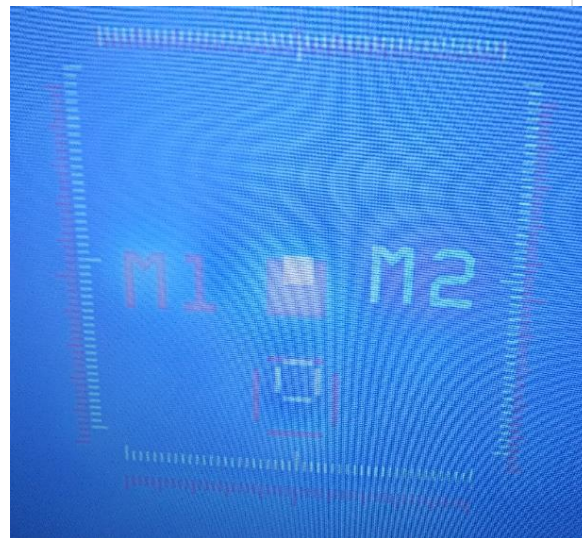
- Spread is nicely grouped
- Each site is consistent
 - print to print
 - stamp to stamp



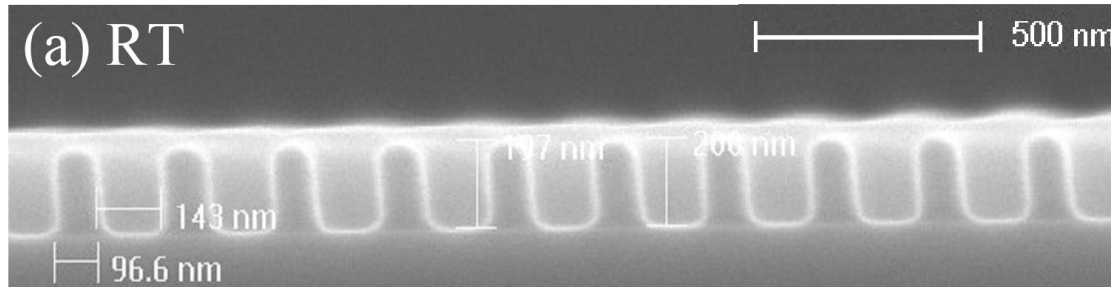
200mm wafer, 16 markers

Overlay result 200mm

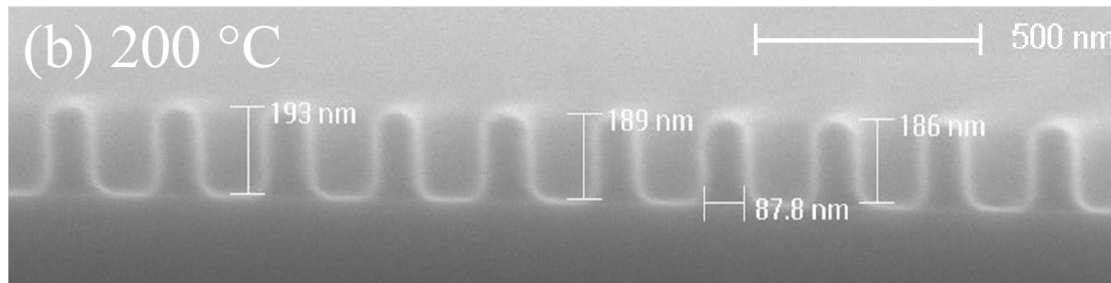
- Blank wafer
- Imprint 1st layer
- Coat with high index for contrast
- Align and imprint 2nd layer
- Used thermo cycling (worst case)
- Observation:
 - Magnification error
 - Pattern shift
- Initial results OK
- Aim to go below 1 μ m



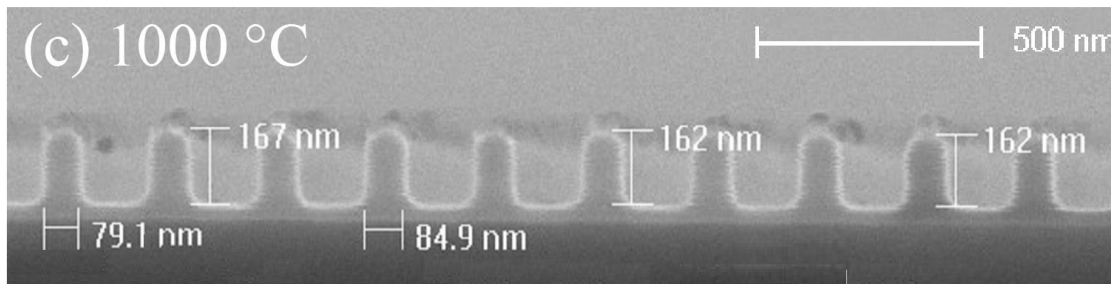
High SiO₂ density @ RT → Low shrinkage



As imprinted (RT)
= 73% dense silica



200 °C =
84% dense silica



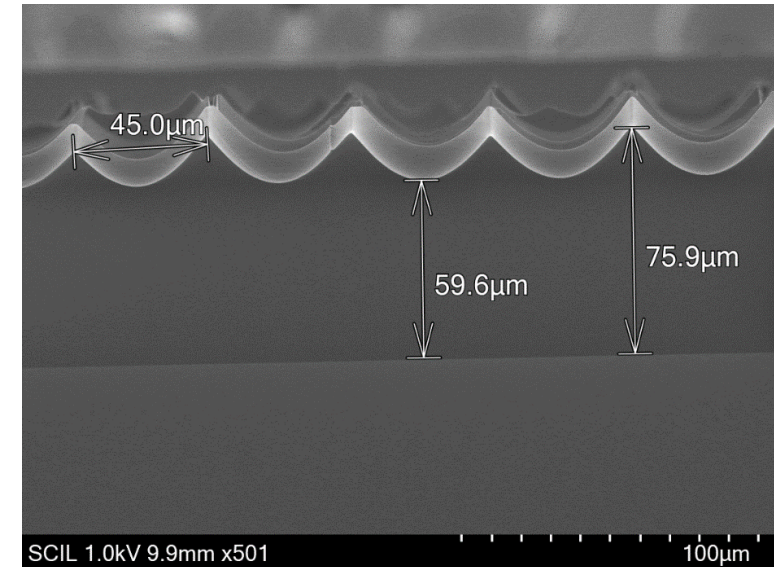
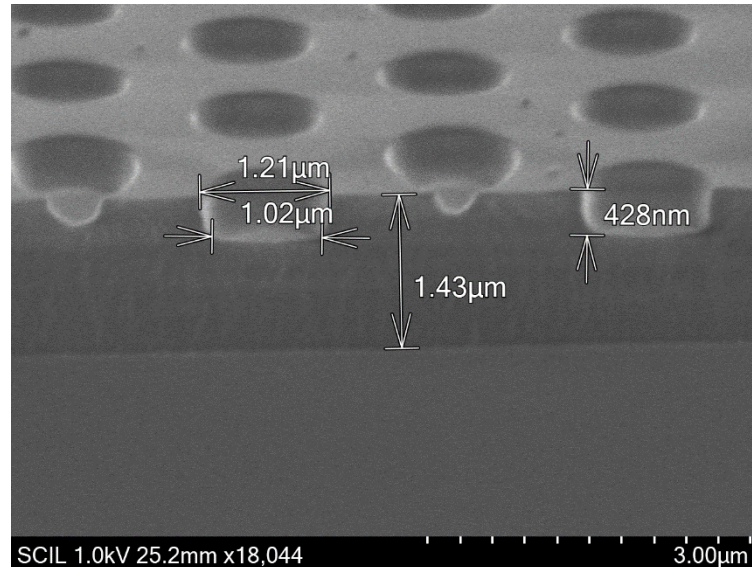
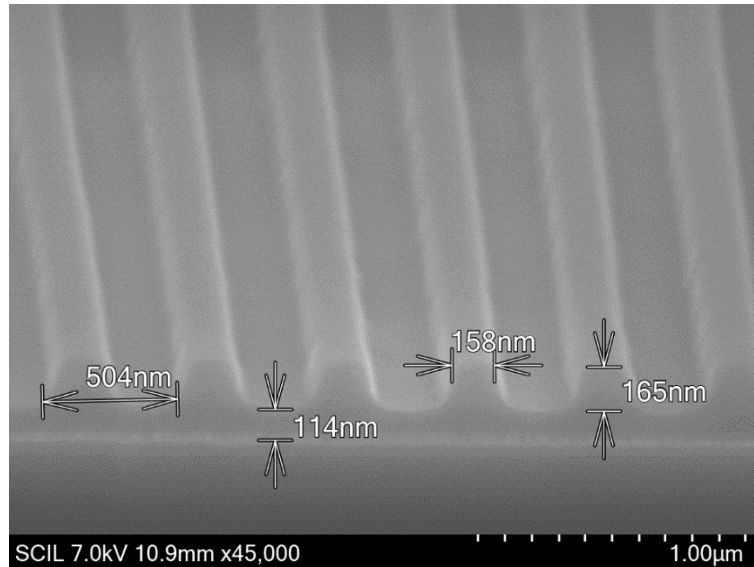
1000 °C =
100% dense silica

SEM cross section of sol-gel grating on silicon

Shape retention

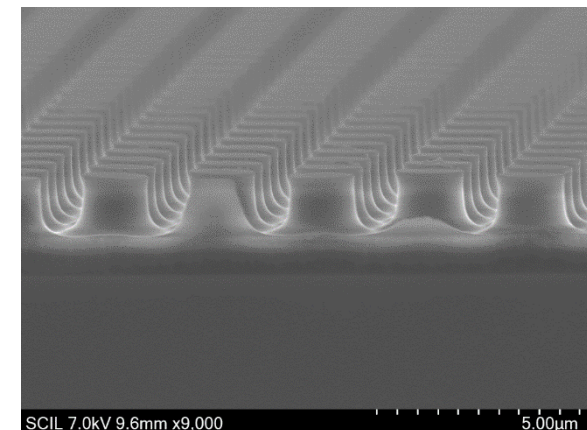
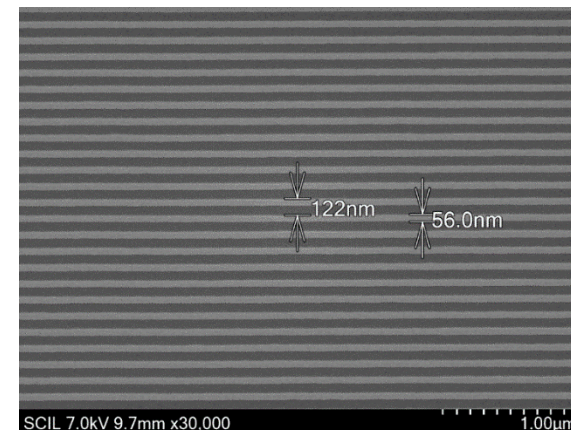
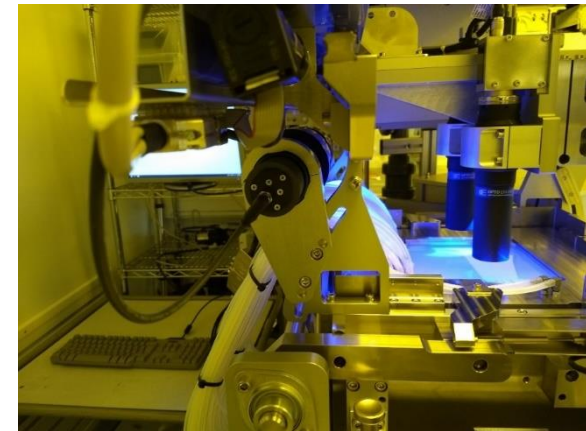
UV curing fully organic imprint resist (under development)

- Some processes require a fully organic imprint resist
- PDMS stamp compatible
- Layers from 100nm to ~50 micron
- Non-absorbing for visible light
- Refractive index $\sim n=1.6$

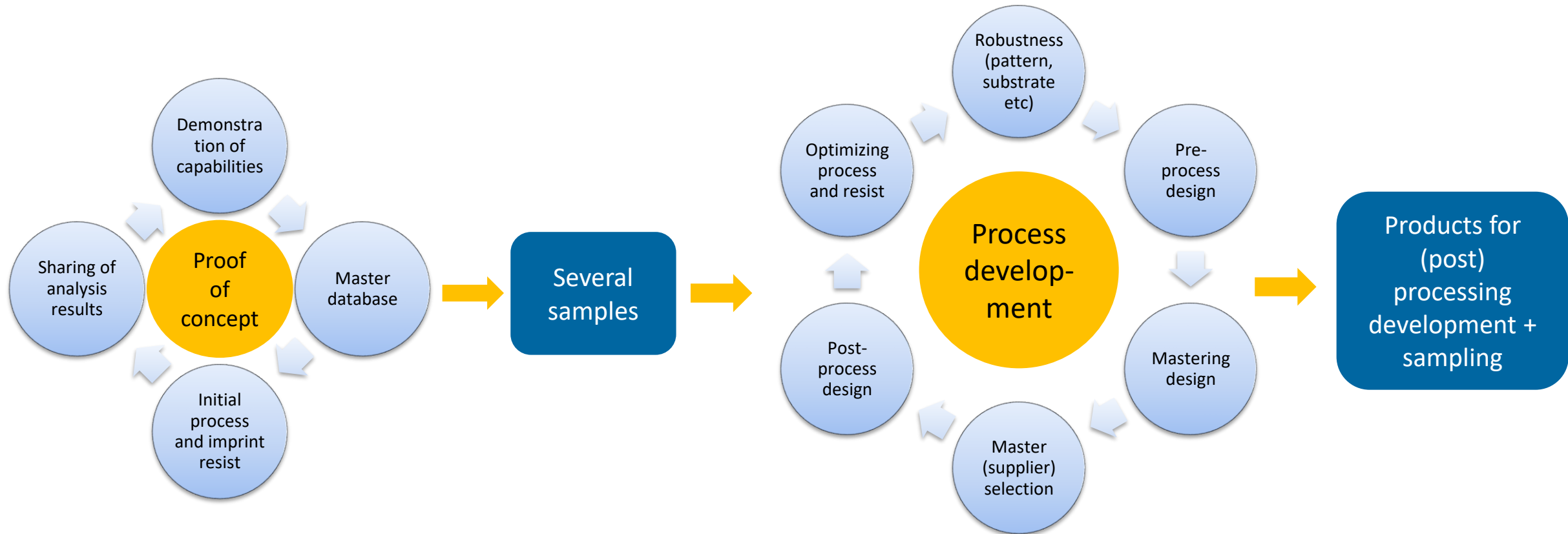


Last year achievements

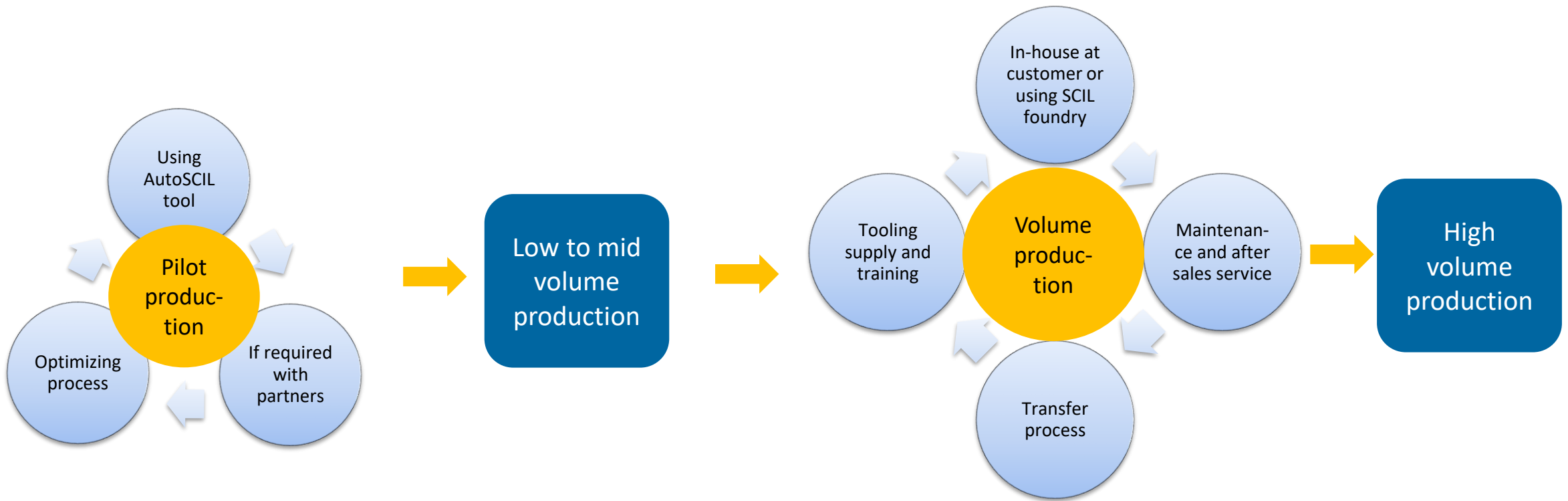
- Two tools installed @ customers
 - **AutoSCIL150**: 3", 4" and 6" wafers
 - **AutoSCIL200DS**: 200mm wafers with overlay alignment
- Equipment development:
 - **LabSCIL200**: Stand alone 200mm imprint tool
 - **AutoSCIL300**: 300mm SCIL tooling
- Stamp manufacturing
 - Semi-automatic tooling available from now
 - Started development of fully automatic tooling
- Wafer scale overlay alignment successfully introduced:
 - Initial overlay X, Y $\sim 1\ \mu\text{m}$ (3-sigma)
 - Front-to-front and front-to-back
 - < 6 sec. for fully automatic alignment
- Materials
 - Fully inorganic, light & temperature stable
 - Low & high index
 - Silica NanoGlass thickness range increased up to $2\ \mu\text{m}$



Sampling and process development



From low to high volume production



This presentation was presented at EPIC Meeting on Wafer Level Optics 2019

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